IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: M. ARIFUKU, et al.

Serial No.: 10/541,380

Filed: JULY 6, 2005

For: CIRCUIT CONNECTING MATERIAL, FILM-FORM CIRCUIT

CONNECTING MATERIAL USING THE SAME, CIRCUIT MEMBER CONNECTING STRUCTURE AND METHOD OF

MANUFACTURING THE SAME

Group AU: 1793

Examiner: Kallambella M. Vijayakumar

Confirm. No: 8734

INFORMATION DISCLOSURE STATEMENT UNDER 37 CFR 1.97 & 1.98

Mail Stop: AMEND – NO FEE Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

February 23, 2010

Sir:

Pursuant to Applicants' duty of disclosure, enclosed herewith please find a copy of an Official Action issued on November 23, 2009, in a counterpart Taiwanese patent application, together with copies of documents cited therein. Also enclosed is an English abstract of the cited JP 2001-160568, and English descriptions of the cited TW 525252, TW 502353 and TW 200304935. Also enclosed is a Form PTO/SB/08A, listing the enclosed documents.

The enclosed Information Disclosure Statement additionally cites EP 996321, JP 11-329069 and JP 2000-208178. These three (3) cited documents have previously been cited and submitted in the above-identified application, with the Information Disclosure Statement filed April 28, 2006 or the Information Disclosure Statement filed January 28, 2009.

This Information Disclosure Statement is being submitted in an application

Docket No. 1303.45151X00 Appln. No. 10/541,380

February 23, 2010

under a pending Final Office Action (that is, the Office Action mailed December 16,

2009). For satisfying requirements of 37 CFR 1.97(d), the necessary fee under

37 CFR 1.17(p) is enclosed, and the following Statement is made under

37 CFR 1.97(e):

Each item of information contained in this Information Disclosure Statement was first cited in any communication from a foreign patent office in a sounterpart foreign patent application not more than

counterpart foreign patent application not more than three months prior to the filing of this Information

Disclosure Statement.

While the enclosed documents are not in English, it is respectfully submitted

that requirements of 37 CFR 1.98(a)(3) are satisfied, at least in connection with the

documents cited in the enclosed Official Action, by English abstracts/descriptions in

connection with the non-English language documents.

In view of the foregoing, it is respectfully submitted that all applicable

requirements of 37 CFR 1.97 and 1.98 have been satisfied, at least in connection

with the documents cited in the enclosed Official Action and enclosed herewith.

Consideration of the enclosed documents, upon further examination of the above-

identified application, is respectfully requested.

Please charge any shortage of fees due in connection with the filing of this

paper to the Deposit Account of Antonelli, Terry, Stout & Kraus, LLP, Deposit

Account No. 01-2135 (case No. 1303.45151X00), or credit any excess fees paid to

such Deposit Account.

Respectfully submitted,

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